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# **MEMS PACKAGING MARKETS AND TRENDS**

***FIRST EDITION***

**A Strategic Report on Device-Level Packaging  
of MEMS Semiconductor Products**

## **Report Highlights**

- **Technology Reviews**
  - ◆ **Microphones**
  - ◆ **Accelerometers/Gyroscopes**
  - ◆ **Pressure Sensors**
  - ◆ **Actuators**
  - ◆ **Others**
- **Product and Company Highlights**
- **Market Analysis and Forecasts, 2007–2012**

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# MEMS PACKAGING MARKETS AND TRENDS

## Synopsis

Although it is a relatively new technology, the MEMS (micro-electromechanical systems) market for actuators, accelerometers, gyroscopes, pressure sensors, and microphones has become a substantial force in the semiconductor industry. Other MEMS products also show promise.

The manufacturing processes of integrated circuits (ICs) are the model used for the manufacture of MEMS devices. Not only are MEMS being created on wafers, but they are being combined in most cases with ICs within variations of standard IC packages. As such, MEMS package assembly has become a topic of great interest to the overall semiconductor packaging industry.

*New Venture Research* (NVR) in its report,

**MEMS Packaging Markets and Trends**, uses information from semiconductor industry insiders to present the most realistic picture available regarding packaging technologies and markets for key MEMS products.

Chapter 1 of the report explains the scope and methodology of the report, while Chapter 2 summarizes the report's key market data.

Chapter 3, **Technical Trends**, presents a concise technical overview of the MEMS market. Topics include applications, device fabrication

Chapter 4, **Product and Company Highlights**, presents the newest packaging products and latest research from over 70 companies and organizations. This presentation is organized into 17 categories of products and services.

Chapter 5, **Forecasts**, presents information on the sensor and actuator products that define the majority of the robust MEMS market. Products include accelerometers and gyroscopes, pressure sensors, microphones, and various actuators.

Forecasts of these MEMS markets include units, package assembly prices, average I/O counts, average assembly costs, and package assembly revenue. The MEMS packaging market is poised for substantial growth in the coming years.

**MEMS Packaging Markets and Trends** will provide you with an effective and economical tool for assessing the future of the MEMS packaging market. Please take a few moments to review the report's outline on the following pages. The report is delivered by email as a single-user PDF file. The report sells for \$1995, with extra single-user licenses at \$250 each. Corporate licensing is available—contact us for pricing.

## About the Author

**Sandra Winkler** is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry nearly 20 years ago. Since 1995, Ms. Winkler has authored all of NVR's widely cited reports on IC packaging. She has spoken at numerous industry conferences and is a contributing editor for Chip Scale Review magazine. Ms. Winkler has an MBA from Santa Clara University.

# MEMS PACKAGING MARKETS AND TRENDS

## Table of Contents

### Chapter 1: Introduction

### Chapter 2: Executive Summary

### Chapter 3: Technical Trends

Overview

Applications

Device Fabrication

Bulk Micromachining

Surface Micromachining

LIGA

Actuation Methods

Device-Level Testing

Packaging Options

Key Issues

Package Types

Encapsulation

### Chapter 4: Product and Company

#### Highlights

Accelerometers

Actuators Adaptive

Optics Chemical

Sensors Displays

Gyroscopes Inertia

Sensors Insulin

Pumps

Microphones

Micromirrors

Oscillators/Resonators

Pressure Sensors

RF MEMS

Viscosity Sensors

Foundries and Multi-MEMS Products

Packaging Contractors and

Prototype/Qualification Services

Substrates

### Chapter 5: Forecasts

Microphones

Accelerometers and Gyroscopes

Pressure Sensors

Actuators

### Partial List of Figures and Tables

Release of MOEMS Structure

Early Microresonator

Polysilicon Integrated Timing Reference

Poly-SiGe MEMS on Top of CMOS

Poly-SiGe Disk Resonators

Basic Principle of a MEMS Microphone

Bulk Micromachined Silicon Crystal

Surface Micromachining

CerPak

SEM Image of Metal Added to the Proof Mass

Multiple Sensing Gaps GS3

Sensor Chip

GS3 Function

Microstrip Patch Antenna

Schematic of 3-D MEMS Chemical Sensor

Flip Chip Version of VI-MEMS Concept

Liquid Crystal Cell Process

Discera Packaged MEMS Resonator

Schematic Three-Dimensional View of RF MEMS Package

Schematic of the Package Process Flow

Schematic Design of 3-D Multilayer Module

Schematic Diagram of an LCP Surface-Mount Package

Bosch Pressure Sensor Housing Options

MEMS Microphone Market, 2007–2012

MEMS Microphone Packages, 2007–2012

MEMS Microphone Price per I/O for Package Assembly, 2007–2012

MEMS Microphone Average Package Price, 2007–2012

MEMS Microphone Packaging Revenue, 2007–2012

MEMS Accelerometer and Gyroscope Market, 2007–2012

MEMS Accelerometer and Gyroscope Packages, 2007–2012

MEMS Accelerometer and Gyroscope Package Assembly Price per I/O, 2007–2012

MEMS Accelerometer and Gyroscope Average I/O Count by Package Type, 2007–2012

MEMS Accelerometer and Gyroscope Average Package Assembly Price, 2007–2012

MEMS Accelerometer and Gyroscope Packaging Revenue, 2007–2012

MEMS Pressure Sensor Market, 2007–2012

MEMS Pressure Sensor Packages, 2007–2012

MEMS Pressure Sensor Average Package Assembly Price per I/O, 2007–2012

MEMS Pressure Sensor Average I/O Count by Package Type, 2007–2012

MEMS Pressure Sensor Average Package Assembly Price, 2007–2012

MEMS Pressure Sensor Packaging Revenue, 2007–2012

MEMS Actuator Market, 2007–2012

MEMS Actuator Packages, 2007–2012

MEMS Actuator Average Package Assembly Price per I/O, 2007–2012

MEMS Actuator Average I/O Count by Package Type, 2007–2012

MEMS Actuator Average Package Assembly Price, 2007–2012

MEMS Actuator Packaging Revenue, 2007–2012

# MEMS PACKAGING MARKETS AND TRENDS

## Table of Contents (continued)

The new products, services, and research of these companies and organizations are presented in Chapter 4 of the report:

Akustica	Innovative Micro Technology	Samsung
Amkor Technology	InvenSense	Sandia National Laboratories
Analog Devices	Jazz Semiconductor	Seiko Epson Corporation
ASE	Knowles Acoustics	Semefab (Scotland) Ltd.
Bennington Microtechnology Center	Kyocera	SEMPAC
Bosch Automotive Electronics	Matsushita Electric Works	Sensorcon
Bosch Sensortec	Mems Technology	Silex Microsystems
Boston Micromachines	MEMSCAP	SiTime
Carsem	MEMX	Sonion MEMS
Colibrys	Micralyne	Spectra-Mat
DALSA Semiconductor	microFAB Bremen	STMicroelectronics
Debiotech	Midwest MicroDevices Miradia	Teledyne
Discera	Momentive Performance Materials	TeraVista Technologies
Ecliptek Corporation	NASA	Texas Instruments
Engent	NeoPhotonics	The Bergquist Company
Fraunhofer Institute	Norcada	Tokimec
Freescale	NXP Semiconductors	Tronics Microsystems
GE Sensing	Oki Electric Industry	TSMC
Gladiator Technologies Hamamatsu	Olympus	University of California at Davis
Photonics	Omron Electrical Components	VTI Technologies Oy
Hana Group	Philips Research	WiSpry
Honeywell	Plan Optik AG	X-FAB
IBM	QUALCOMM MEMS Technologies	Yamaha
IMEC	Quantum Leap Packaging	
Infineon		

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